

X0066

N-Channel Enhancement Mode MOSFET

60V(VDS) / ± 20 V(VGS) / 80A(ID)

Rev1.1



Wafer Specification

1. Order Information

Part No.	Description	Gross die / per 8" wafer
X0066	60V(V_{DS}) / $\pm 20V(V_{GS})$ / 80A(I_D) N-Channel Enhancement Mode MOSFET	4,870

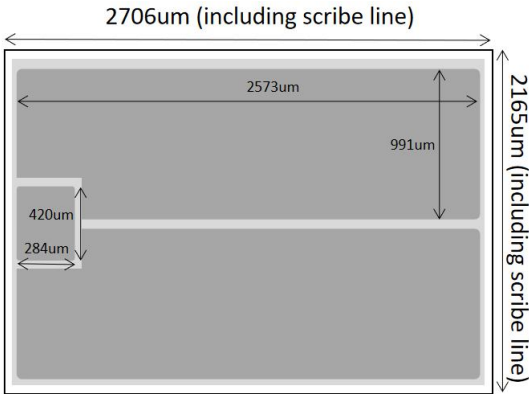
2. Mechanical Data

Nominal Back Metal Composition, Thickness	Ti-Ni-Ag (13kÅ°)
Nominal Front Metal Composition, Thickness	AlCu (4µm)
Wafer Diameter	200mm, with 010 notch
Wafer Thickness	150µm±10µm
Scribe Line Width	60µm
Passivation	SRO+SiN

3. Key Electrical Characteristics of Die (at $T_J = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Description	Min.	Typ.	Max.	Unit	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	60			V	$V_{GS}=0V$, $I_D=250\mu A$
$I_{D(\text{Device Ref})}$	Continuous Drain Current			80	A	$T_J=25^\circ\text{C}$
$R_{DS(on)(CP)}$	Static Drain-to-Source On-Resistance		4.5	11	mΩ	$V_{GS}=10V$, $I_D=1A$
$R_{DS(on)(FT)}$	Static Drain-to-Source On-Resistance		5.3	7	mΩ	$V_{GS}=10V$, $I_D=30A$
$V_{GS(th)}$	Gate Threshold Voltage	2	3	4	V	$V_{DS}=V_{GS}$, $I_D=250\mu A$
I_{DSS}	Drain-to-Source Leakage Current		0	1	µA	$V_{DS}=60V$, $V_{GS}=0V$
I_{GSS}	Gate-to-Source Leakage Current		0	±100	nA	$V_{GS}=\pm 20V$, $V_{DS}=0V$
T_J , T_{STG}	Operating and Storage Temperature	-55°C to 150°C Max				

4. Die Outline

	Die Size: 2706µm × 2165µm (including scribe line)
	Gate: 284µm × 420µm
	For TO-220C package Suggest Bonding wire: Gate: 1 × 5 mil Al Source: 4 × 15 mil Al